

N-Channel 800V (D-S) Super Junction Power MOSFET

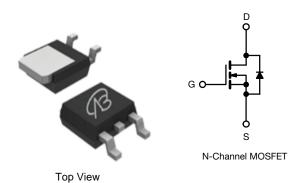
PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	800				
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.510			

FEATURES

- Low figure-of-merit (FOM) Ron x Qa
- Low input capacitance (Ciss)
- Reduced switching and conduction losses
- Ultra low gate charge (Qg)
- Avalanche energy rated (UIS)



TO-252



APPLICATIONS

- Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
- Battery chargers
- Renewable energy
- Solar (PV inverters)

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)					
PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V_{DS}	800	
Gate-source voltage			V_{GS}	± 30	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \
Continuous drain current (T, = 150 °C)	V at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	- I _D -	9	
Continuous drain current (1) = 150 C)	V _{GS} at 10 V	T _C = 100 °C		5.5	Α
Pulsed drain current ^a			I _{DM}	27	
Linear derating factor				1.7	W/°C
Single pulse avalanche energy b			E _{AS}	320	mJ
Maximum power dissipation			P_{D}	180	W
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C
Drain-source voltage slope	T _J = 125 °C		dV/dt 50	V/ns	
Reverse diode dV/dt ^d		uv/di	5.1	V/IIS	
Soldering recommendations (peak temperature) c	For 10 s			260	°C

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 100 V, starting T_J = 25 °C, L = 30 mH, R_g = 25 Ω , I_{AS} = 4A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, $dI/dt = 100 \text{ A/}\mu\text{s}$, starting $T_J = 25 \,^{\circ}\text{C}$



THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	0.85	C/VV	

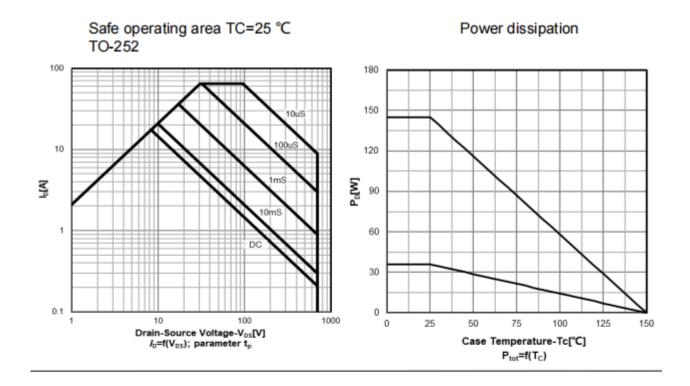
PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static						•	
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		800	_	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	1.08	-	V/°C
Gate-source threshold Voltage (N)	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		2.0	-	4.0	V
		V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I _{GSS}		$V_{GS} = \pm 30 \text{ V}$		-	± 1	μΑ
		V _{DS} =	$V_{DS} = 800 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 640 \text{ V}, V_{GS} = 0 \text{ V}, T_J = 125 ^{\circ}\text{C}$		-	1	μА
Zero gate voltage drain current	I _{DSS}	V _{DS} = 640 \			=	10	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D =3A	-	0.510	-	Ω
Forward transconductance	9 _{fs}	V_{DS}	= 30 V, I _D = 5 A	-	8.7	-	S
Dynamic		,					
Input capacitance	C _{iss}		V _{GS} = 0 V,	_	2200	_	
Output capacitance	C _{oss}	1	$V_{DS} = 100 \text{ V},$	-	51	-	
Reverse transfer capacitance	C _{rss}	1	f = 1 MHz		12	-	pF
Effective output capacitance, energy related ^a	C _{o(er)}	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	48	-	
Effective output capacitance, time related ^b	C _{o(tr)}			-	205	-	
Total gate charge	Qg			-	25	-	1
Gate-source charge	Q _{gs}	V _{GS} = 10 V	$V_{GS} = 10 \text{ V}$ $I_D = 5 \text{ A}, V_{DS} = 480 \text{ V}$		8	-	nC
Gate-drain charge	Q _{gd}	1			10	-	
Turn-on delay time	t _{d(on)}			-	12	24	
Rise time	t _r	Von	$V_{DD} = 480 \text{ V}, I_D = 5 \text{ A}, V_{GS} = 10 \text{ V}, R_q = 9.1 \Omega$		14	23	ns
Turn-off delay time	t _{d(off)}	V _{GS}			61	110	
Fall time	t _f		J	-	16	-	1
Gate input resistance	R_g	f = 1 MHz, open drain		0.3	0.7	1.4	Ω
Drain-Source Body Diode Characteristic	s						•
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	9	
Pulsed diode forward current	I _{SM}			-	-	27	- A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 5 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 5 \text{ A},$ $dI/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	416	832	ns
Reverse recovery charge	Q _{rr}			-	6.4	12.8	μC
Reverse recovery current	I _{RRM}			_	27	-	Α

Notes

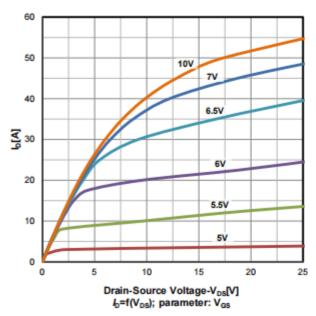
- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS} b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}



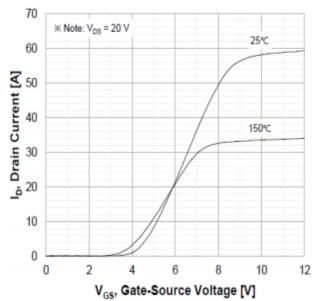
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Typ. output characteristics T_i =25 $^{\circ}C$

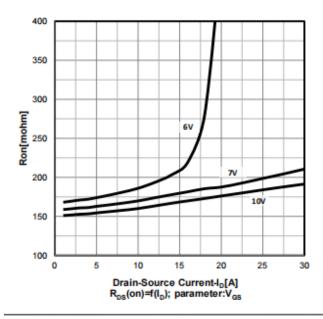


Transfer characteristics

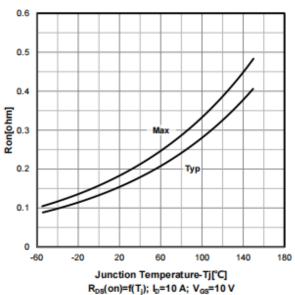




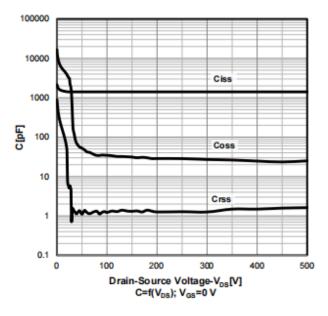
Typ. drain-source on-state resistance



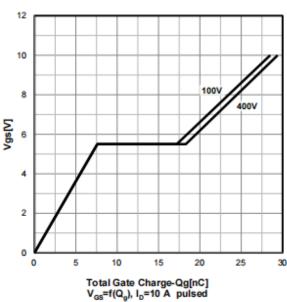
On-resistance vs temperature



Typ. capacitances



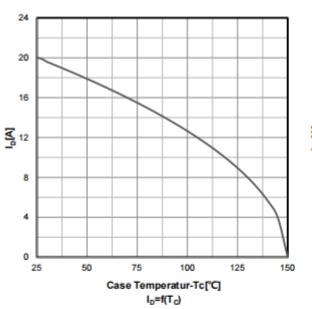
Typ. gate charge characteristics

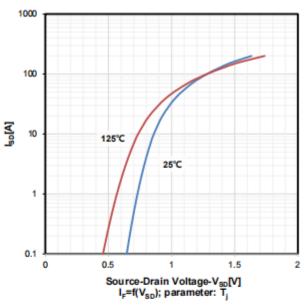




Drain current vs temperature

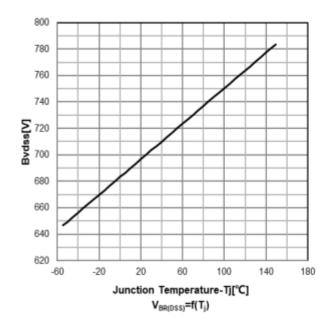
Forward characteristics of reverse diode

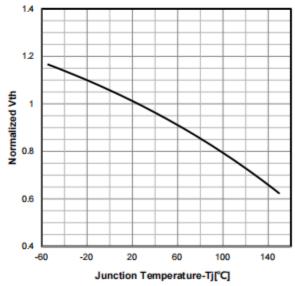




Drain-source breakdown voltage

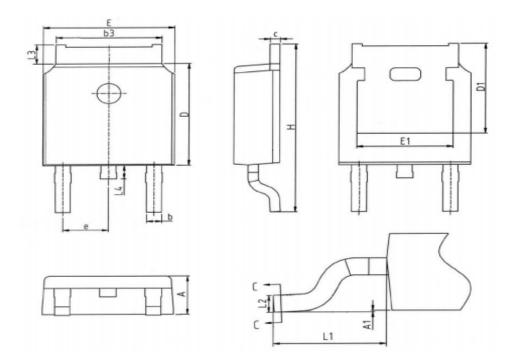
Normalized $V_{\text{GS}(\text{th})}$ characteristics







Package Outline: TO 252



COMMON DIMENSIONS

SYMBOL	UNIT(mm)				
SIMBOL	MIN	NOM	MAX		
A	2.20	2.30	2.40		
A1	0.00	-	0.127		
b	0.66	0.78	0.90		
b3	5.16	5.31	5.46		
с	0.43	0.53	0.63		
D	5.98	6.10	6.22		
D1	5.30REF				
E	6.40	6.60	6.75		
E1	4.63	-	-		
e	2.286BSC				
H	9.40	10.10	10.50		
L1	2.90REF				
L2	0.51BSC				
L3	0.88	1.08	1.28		
L4	0.50	0.80	1.00		



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